General purpose (dual digital transistor)

**Datasheet** 

Parameter	DTr1 and DTr2
V <sub>CEO</sub>	50V
I <sub>C</sub>	100mA
R <sub>1</sub>	4.7kΩ

### Features

- 1)Two DTC143T chips in a EMT or UMT or SMT package.
- 2)Mounting possible with EMT3 or UMT3 or SMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4) Mounting cost and area can be cut in half.

### Outline

SOT-563	SOT-363
EMH3 (EMT6)	UMH3N (UMT6)
SOT-457 (4) (5) (6) (6)	

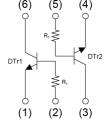
## •Inner circuit

### EMH3 / UMH3N

**ІМН3А** 

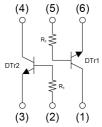
(SMT6)

- (1) DTr1 Emitter
- (2) DTr1 Base
- (3) DTr2 Collector
- (4) DTr2 Emitter
- (5) DTr2 Base
- (6) DTr1 Collector



## IMH3A

- (1) DTr1 Collector
- (2) DTr2 Base
- (3) DTr2 Emitter
- (4) DTr2 Collector
- (5) DTr1 Base
- (6) DTr1 Emitter



## Application

INVERTER, INTERFACE, DRIVER

## Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
ЕМН3	SOT-563 (EMT6)	1616	T2R	180	8	8000	НЗ
UMH3N	SOT-363 (UMT6)	2021	TN	180	8	3000	НЗ
IMH3A	SOT-457 (SMT6)	2928	T110	180	8	3000	НЗ

# ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

F	Parameter			Unit
Collector-base voltage			50	V
Collector-emitter voltage			50	V
Emitter-base voltage		$V_{EBO}$	5	V
Collector current		I <sub>C</sub>	100	mA
	EMH3	P <sub>D</sub> *1*2	150	
Power dissipation	UMH3N	P <sub>D</sub> *1*2	150	mW/Total
	IMH3A	P <sub>D</sub> *1*3	300	
Junction temperature		T <sub>j</sub>	150	°C
Range of storage tempera	Range of storage temperature			°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

Davanatas	Symbol Conditions -		Values			Unit
Parameter 			Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV <sub>CBO</sub>	I <sub>C</sub> = 50μA	50	-	-	V
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 1mA	50	-	-	V
Emitter-base breakdown voltage	BV <sub>EBO</sub>	I <sub>E</sub> = 50μA	5	-	-	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 50V	-	-	500	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 4V	-	-	500	nA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 5mA, I <sub>B</sub> = 0.25mA	-	-	300	mV
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> = 5V, I <sub>C</sub> = 1mA	100	250	600	-
Input resistance	R <sub>1</sub>	-	3.29	4.7	6.11	kΩ
Transition frequency	f <sub>T</sub> *4	V <sub>CE</sub> = 10V, I <sub>E</sub> = -5mA, f = 100MHz	-	250	-	MHz

<sup>\*1</sup> Each terminal mounted on a reference land



<sup>\*2 120</sup>mW per element must not be exceeded.

<sup>\*3 200</sup>mW per element must not be exceeded.

<sup>\*4</sup> Characteristics of built-in transistor

## ● Electrical characteristic curves (T<sub>a</sub> = 25°C)

<For DTr1 and DTr2 in common>

Fig.1 Grounded Emitter Propagation Characteristics

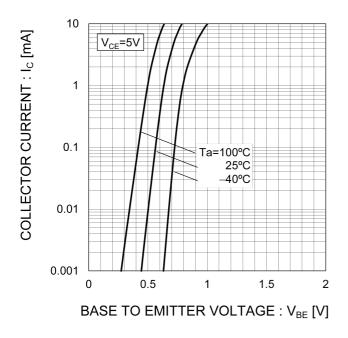


Fig.2 Grounded Emitter Output Characteristics

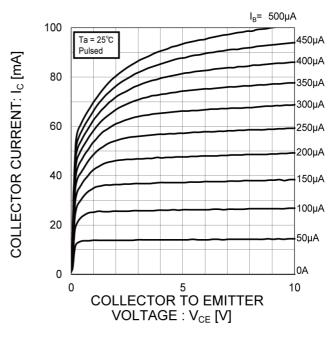


Fig.3 DC Current Gain vs. Collector Current

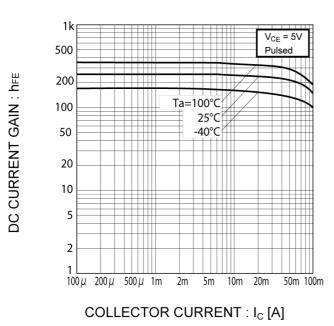
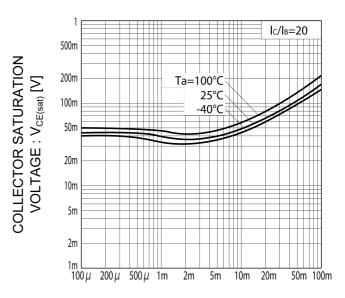
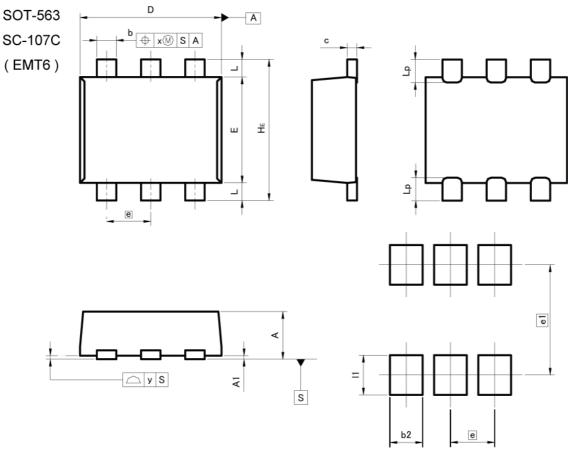


Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

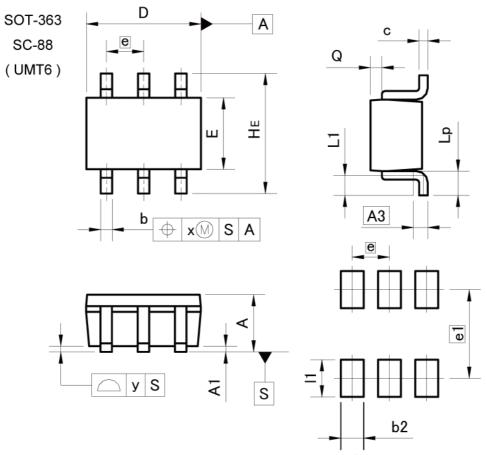
	MILIMETERS		INCHES	
DIM	IVITETIVI	ETERS	INCHES	
Diw	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
е	0.	50	0.020	
HE	1.50	1.70	0.059	0.067
L	0.10	0.30	0.004	0.012
Lp	_	0.35	_	0.014
х	-	0.10	_	0.004
У	_	0.10	-	0.004

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
b2	-	0.37	_	0.015
e1	1.25		0.0	49
- 11	-	0.45	-	0.018

Dimension in mm/inches



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

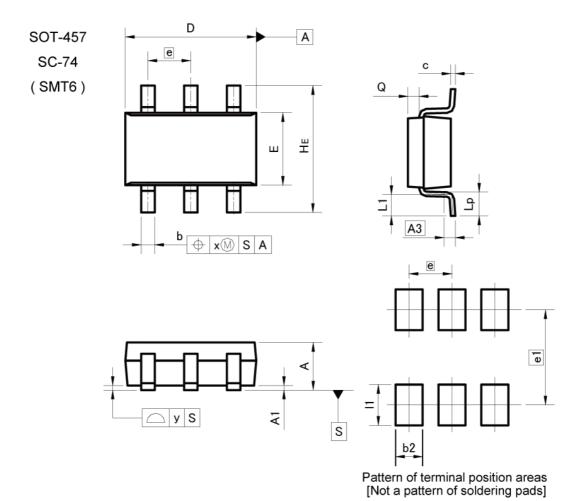
DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	0.80	1.00	0.031	0.039	
A1	0.00	0.10	0.000	0.004	
A3	0.3	25	0.0	10	
b	0.15	0.30	0.006	0.012	
С	0.10	0.20	0.004	0.008	
D	1.90	2.10	0.075	0.083	
E	1.15	1.35	0.045	0.053	
е	0.0	65	0.026		
HE	2.00	2.20	0.079	0.087	
L1	0.20	0.50	0.008	0.020	
Lp	0.25	0.55	0.010	0.022	
Q	0.10	0.30	0.004	0.012	
х	-	0.10	e=	0.004	
у	- 7	0.10	-	0.004	

1	DIM	MILIMETERS		INCHES	
	DIM	MIN	MAX	MIN	MAX
	b2	- 7	0.40	j -	0.016
	e1	1.55		0.0	61
	11	-	0.65	-	0.026

Dimension in mm/inches



## Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.:	25	0.0	10
b	0.25	0.40	0.010	0.016
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.9	95	0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	-	0.20	-	0.008
у	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
b2		0.60	-	0.024
e1	2.10		0.0	83
11	<del>-</del> -2	0.90	===	0.035

Dimension in mm/inches



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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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